



The 5th IEEE International Conference on Consumer Electronics – Berlin, 6 – 9 September 2015



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CALL FOR PAPERS

The 5th IEEE International Conference on Consumer Electronics – Berlin (“ICCE-Berlin”) will be held from the 6th to 9th September 2015 in Berlin in parallel with the IFA, the leading trade show for Consumer Electronics and Home Appliances. The ICCE-Berlin is the European sister conference of the IEEE Consumer Electronics Society’s flagship conference “ICCE” held annually in Las Vegas in conjunction with the Consumer Electronics Show. Now in its 5th edition, ICCE-Berlin is well established and fully integrated in the IFA and continuously growing. This year the IEEE CE Society is joining forces with other IEEE societies to broaden and strengthen the CE subjects and scope of the conference.

Berlin, a birthplace of consumer electronics, is one of Europe’s most exciting cultural centres and a vibrant city. The conference will again bring together researchers and engineers from industry, research centres, and academia to exchange information and results of recent work on systems, circuits, technologies, processes, and applications. It will provide an excellent forum for the researchers, system developers, and service providers to share their ideas, designs and experiences in such a proper environment as the IFA.

IEEE 2015 ICCE-Berlin is asking you for submissions of technical papers for oral and poster presentations. Prospective authors are invited to submit a 2-page abstract in any of the technical areas below as well as in other areas related to consumer electronics. The final paper may extend up to 5 pages. All accepted and presented papers will be submitted to IEEE Xplore for publishing. Student papers are particularly encouraged. The conference includes but is not limited to the following topics:

Audio and Video Technology

- DVBT and HDTV
- Audio Image and Video Processing
- Audio-Visual Recording and Storage
- Display Systems
- HD, UHD and 3D Video
- Smartphone
- Universal Touch Pad Application

Entertainment and Games

- Silver Games
- Video Handheld
- IPTV-Game System
- Networked AV/Multimedia

Car Electronics

- Automotive Computing
- AV & In Car Networking
- Driver Assistance
- Automotive Entertainment

Consumer Networks

- Smart Home
- Home Networking, Home Gateways
- Emerging Network Architectures
- Networking Standards
- Security and Privacy
- Data in the Cloud

RF & Wireless

- Antennas
- Modulation and Coding
- Software Radio
- Spectrum Usage
- Channel Equalization, MiMo, Diversity
- Mobile Reception

Human-Device Interaction

- User Centered Design
- Usability/Accessibility
- Haptics

Sports, Wellness and Home Healthcare

- Ambient Assisted Living
- Support systems for people with special demands
- Vital Parameter Monitoring
- Personal Robotics

Smart Energy

- Energy Harvesting and Efficiency
- Energy Generation, Storage and Management
- Smart Energy Devices and Apps
- Smart Grid & CE

Product Safety Engineering

President IEEE CE Society
Sharon Peng, US

VDE Representative
Volker Schanz, DE

International Coordinators
Stephen Dukes, US
Simon Sherratt, UK
Heinz-Helmut Schramm, DE

Important Dates

Extended Abstract Submission Deadline:
19 April 2015

Notification of Acceptance:
17 May 2015

Final Paper Submission Deadline:
7 June 2015

Paper Submission at the ICCE-Berlin website www.icce-berlin.org

Keynote Speakers

Coming soon

Doctoral Workshop for PhD students, and

Young Professionals Short Course: see more at www.icce-berlin.org

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